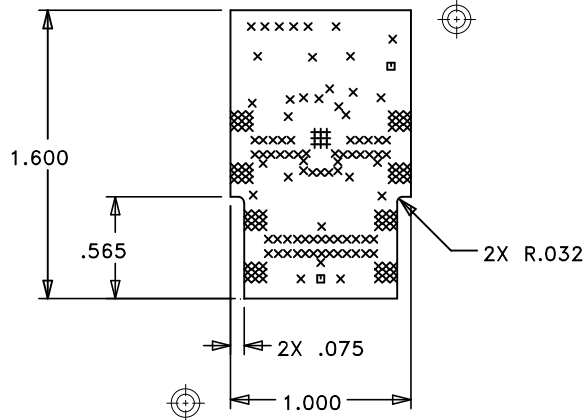
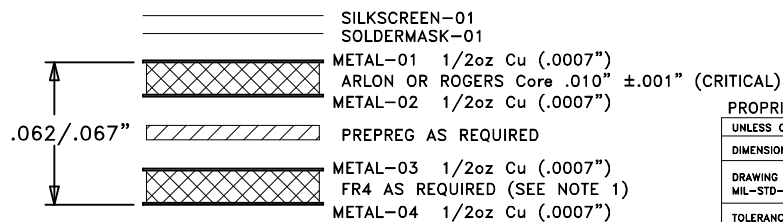


DO NOT SCALE PRINT

HITTITE MICROWAVE  
PCB #118852-2  
DRILL DRAWING

SIZE	QTY	SYM	PLATED	TOL
10	9	+	YES	+/-3
14	159	X	YES	+/-3
43	2	□	YES	+/-3

LAYER	DESCRIPTION
1	RF/GND PLANE
2	GND PLANE
3	GND PLANE
4	BOTTOM GND PLANE



LAYER STACKUP

PROPRIETARY TO HITTITE MICROWAVE CORPORATION

UNLESS OTHERWISE SPECIFIED:	
DIMENSIONS ARE IN INCHES (MM)	
DRAWING PRACTICES PER MIL-STD-100	
TOLERANCES:	
.XX	+/- 0.010
.XXX	+/- 0.005
.XXXX	+/- 0.002
ANGLES	+/- .5 DEG

DWN BY:  
J. DONOVAN 8/27/07  
ENGINEER:HITTITE MICROWAVE CORPORATION  
20 Alpha Road Chelmsford, MA 01824TITLE  
PCB, EVAL  
HMC792LP4E

SIZE	CODE ID NO.	DRAWING NO.	REV
A	1CN88	118852	2
SCALE: NONE		WT	SHEET 1 of 1

NOTES:  
UNLESS OTHERWISE SPECIFIED

1. MATERIAL: MULTILAYER. OVERALL STACKUP AS SHOWN. TYPE ROGERS 4350 OR ARLON 25FR, HALF OUNCE COPPER BOTH SIDES. FR4 TO BE USED AS FILLER TO MEET CRITICAL OVERALL THICKNESS.
2. FINISH: GOLD PLATE PER ASTM B-488, TYPE III, CODE A, 40 TO 100 MICROINCHES, OVER NICKEL PER QQ-N-290, 100 MICROINCHES MINIMUM.
3. PLATED THRU HOLES: .001" MINIMUM WALL THICKNESS.
4. HOLE SIZES AND POSITIONS PER ARTWORK AND/OR DRILL FILE.
5. ALL HOLES TO BE LOCATED WITHIN ±.003" OF THE CENTER OF THE PAD OR OTHER TRUE POSITION.
6. FRONT TO BACK REGISTRATION ±.003" MAX.
7. BOARD WARPAGE: <.010" PER LINEAR INCH.
8. SILKSCREEN TOPSIDE ONLY WITH WHITE EPOXY INK.
9. PLATING THICKNESS .002"±.0005 FOR METAL-01 AND METAL-04.
10. SOLDERMASK: LPI SOLDERMASK TOP SIDE. COLOR: GREEN REGISTRATION: ±.004 MAX.
11. REMOVE METAL BURRS FROM EDGE OF PCB AFTER PANEL SEPARATION.
12. ARTWORK IS 1:1. VENDOR TO ADJUST FOR ETCH FACTOR.
13. "SIZE" IN DRILL LEGEND IS IN MILS AND REFERS TO FINISHED HOLE SIZE.
14. MANUFACTURE PER IPC-600 CLASS 2.

## UNLESS OTHERWISE SPECIFIED

15. CRITICAL LINE WIDTH = .016" ±.001 ADJUST PROCESS TO ACHIEVE WIDTH.